

AMENDMENTS TO THE SPECIFICATI N

Please r place paragraph [0027] with the following amended paragraph:

5 [0027] Please refer to Fig.12. Fig.12 is a schematic diagram of a package according to the present invention. As shown in Fig.12, a package 40 comprises a chip 42, a substrate 44, and a print circuit board 46. An underfill layer 56 is filled in a gap between the chip 42 and the substrate 44. The substrate 44 is a plastic substrate or a ceramic substrate. A plurality of first solder bump pads 52a and a plurality of second solder bump pads 52b are ~~[[is]]~~ located on a first surface of the substrate 44, and each of the first solder bump pads 52a has a smaller diameter than each of the second solder bump pads 52b. ~~and each solder bump pad 52~~ Additionally, each of the first solder bump pads 52a and the second solder bump pads 52b connects to a solder bump 54. ~~The solder bump pads 52, and the first solder bump pads 52a and the second solder bump pads 52b~~ connect to the chip 42 by use of the solder bumps 54. Furthermore, ~~[[A]]~~ a plurality of first solder ball pads 58a and a plurality of second solder ball pads 58b are ~~[[is]]~~ located on a second surface of the substrate 44, and each of the first solder ball pads 58a has a smaller diameter than each of the second solder ball pads 58b. ~~and each solder ball pad 58~~ Each of the first solder ball pads 58a and the second solder ball pads 58b connects to a solder ball 60. ~~The solder ball pads 58, and the first solder ball pads 58a and the second solder ball pads 58b~~ connect to the print circuit board 46 by use of the solder balls 60. Noticeably, in order to make

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the package sustain higher thermal stress and high x fatigue strength, the solder bump pads 52a and 52b or the solder ball pads 58a and 58b should have at least two different kinds of diameters. The second solder bump pads 52b or the second solder ball pads 58b with larger sizes are used to sustain a stronger thermal stress during a thermal process. The arrangement of the first solder bump pads 52a and the second solder bump pads 52b or the solder ball pads 58 can refer to the first embodiment to the seventh embodiment of the present invention. Likewise, the arrangement of the first solder ball pads 58a and the second solder ball pads 58b can refer to the first embodiment to the seventh embodiment of the present invention.

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Please replace paragraph [0028] with the following amended paragraph:

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[0028] In addition, the first solder bump pads 52a and the second solder bump pads 52b can be located on a surface of the chip 42 in the package 40 shown in Fig. 12. Then, each solder bump pad 52 of the first solder bump pads 52a and the second solder bump pads 52b connects to a solder bump 54, and uses the solder bump 54 to connect to the substrate 44. Conversely, the first solder ball pads 58a and the second solder ball pads 58b can be located on a surface of the print circuit board 46. Each solder ball pad 58 of the first solder ball pads 58a and the second solder ball pads 58b connects to a solder ball 60, and uses the solder ball 60 to connect to the substrate 44.